

EE-612:

Lecture 26:

CMOS Limits

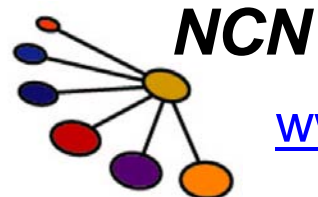
Mark Lundstrom

Electrical and Computer Engineering

Purdue University

West Lafayette, IN USA

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Outline

- 1) Review: CMOS Metrics
- 2) MOSFET limits
- 3) Circuit limits
- 4) System Limits

CMOS metrics

- 1) Switching energy: $E_S = \frac{1}{2} C V_{DD}^2$
- 2) Switching delay: $\tau_S = \frac{C V_{DD}}{I_D(\text{ON})}$
- 3) Dynamic power: $P_D = \alpha f C V_{DD}^2$
- 4) Energy-delay product: $E_S \tau = \frac{1}{2} \frac{C^2 V_{DD}^3}{I_D(\text{on})}$

Outline

- 1) CMOS Metrics
- 2) MOSFET limits**
- 3) Circuit limits
- 4) System limits

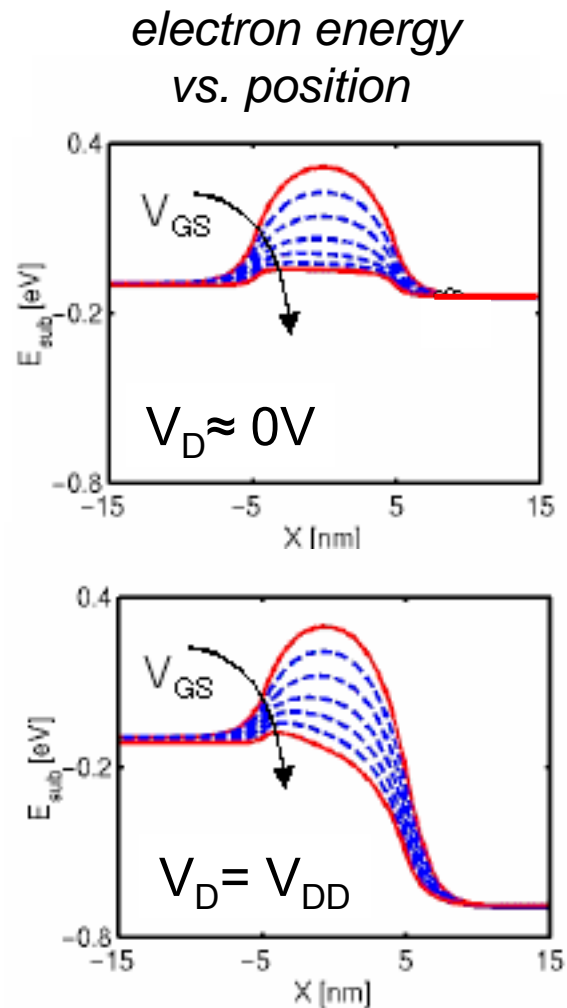
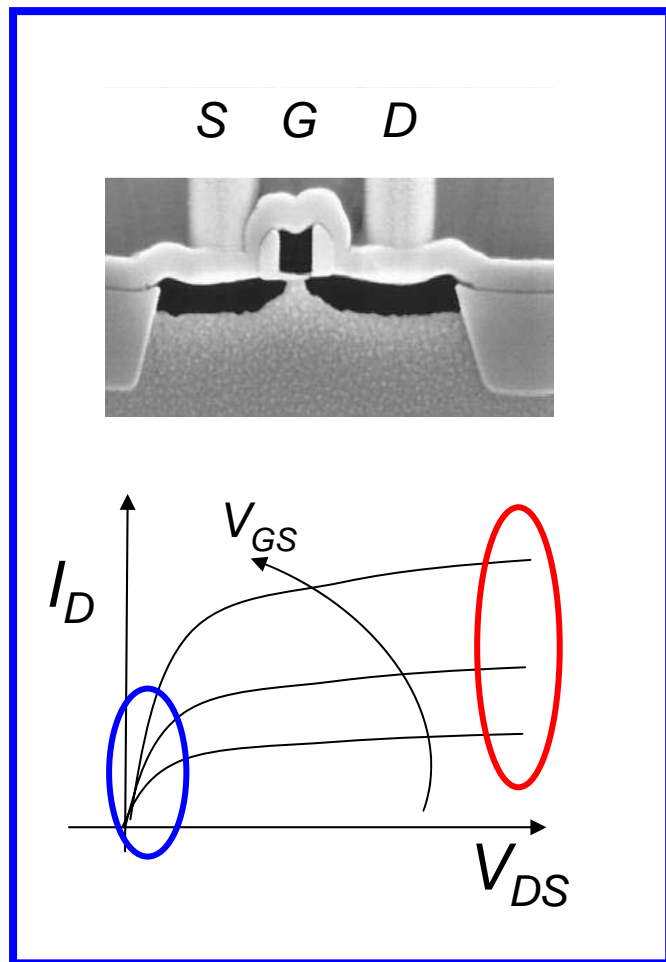
device limit questions

- 1) minimum energy dissipation per logic transition
- 2) minimum channel length
- 3) maximum device density
- 4) minimum device delay
- 5) power density
- 6) power-limited device density
- 7) CMOS vs. the ultimate switch

acknowledgment

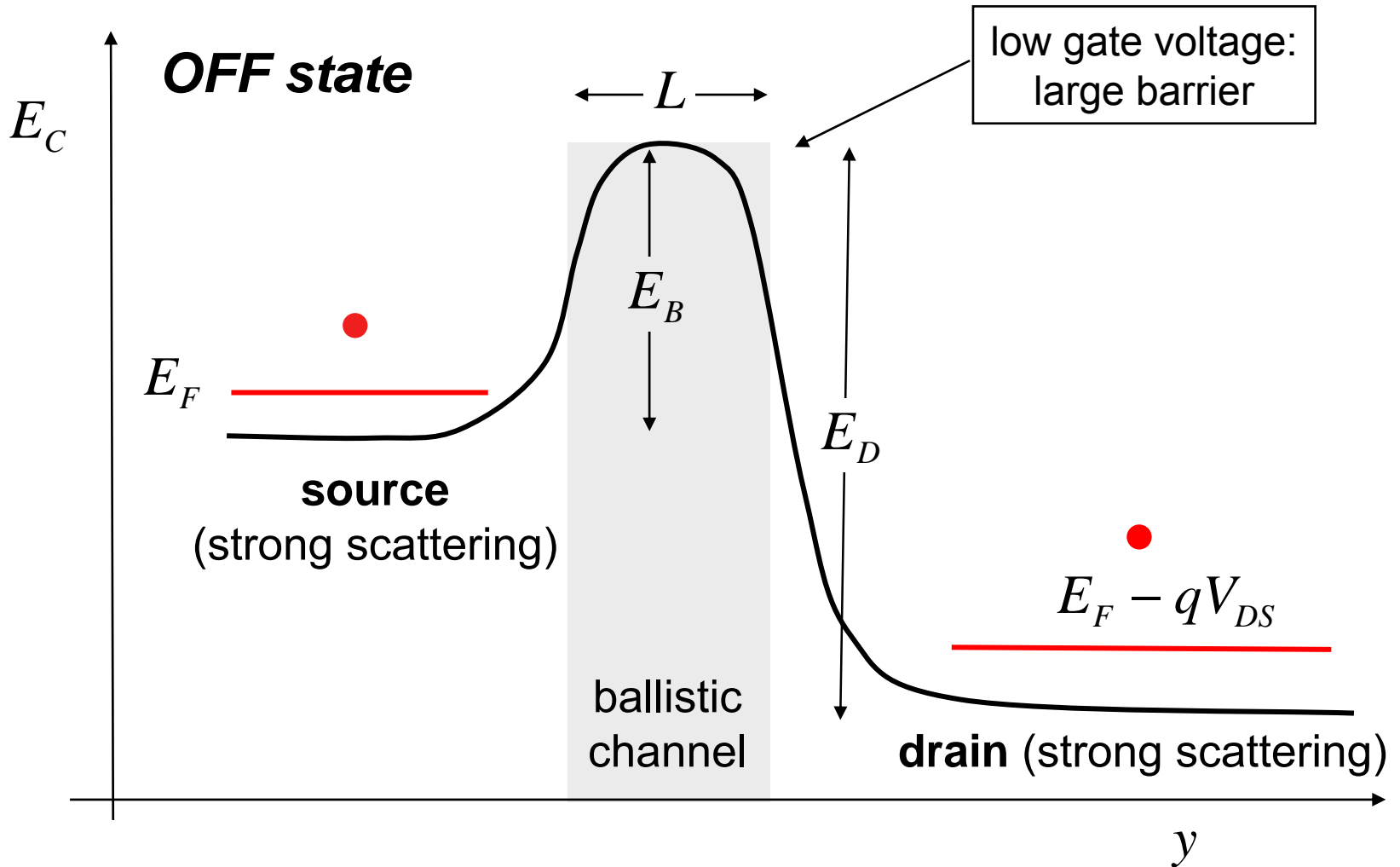
The approach that I take here is similar to the work of V.V. Zhirnov, R.K. Cavin, J.A. Hutchby, and G. Bourianoff, “Limits to Binary Logic Switch Scaling - A Gedanken Model,” *Proc. IEEE*, Special Issue on Nanoelectronics and Nanoscale Processing, Nov. 2003.

MOSFETs control current with potential barriers

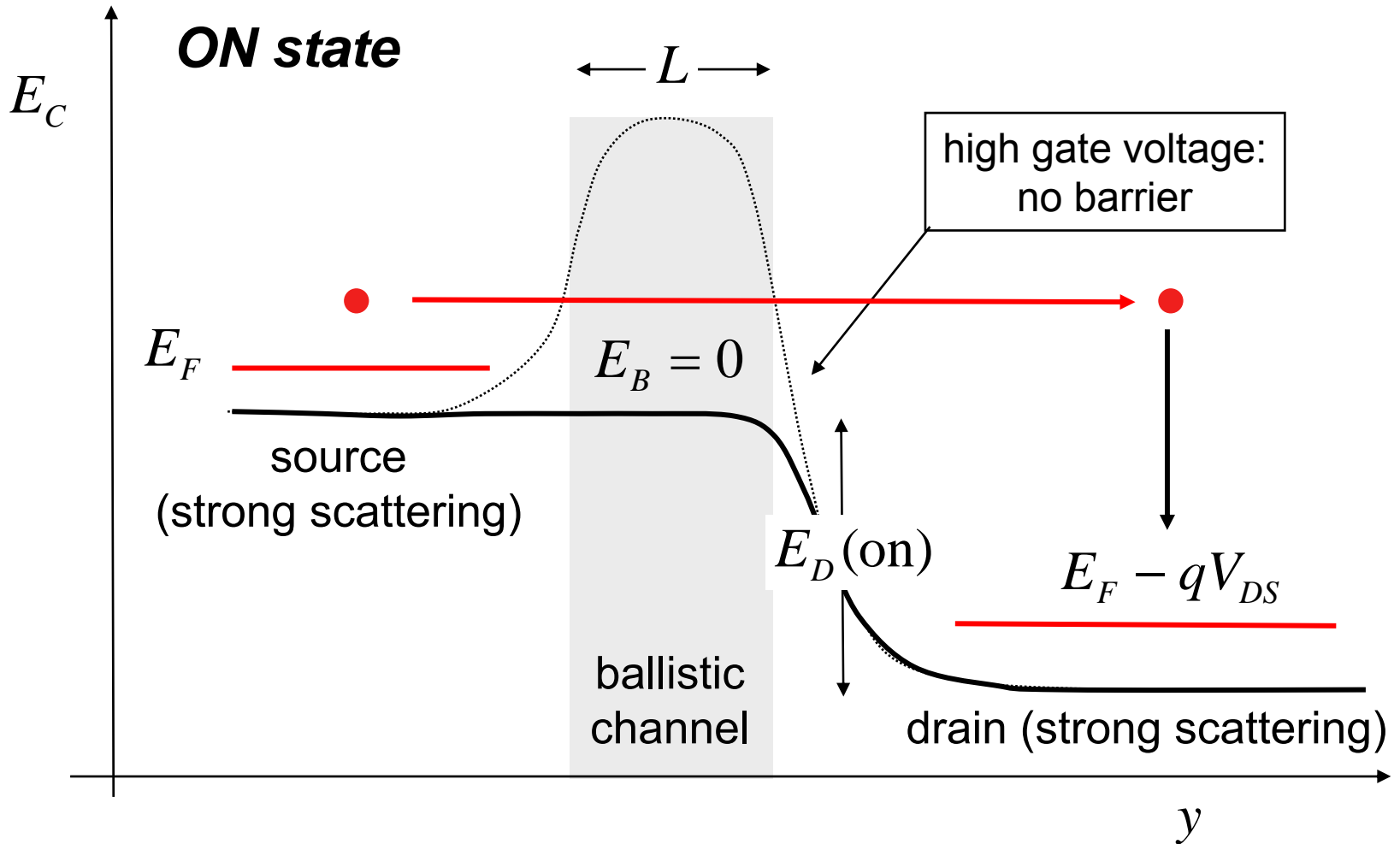


E.O. Johnson, *RCA Review*, 1971

ultimate MOSFET in the off-state



ultimate MOSFET in the on-state

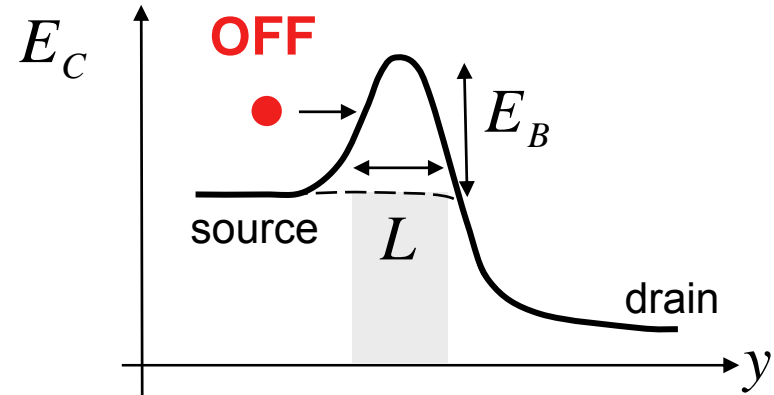


minimum switching energy

To distinguish **off** from **on**, electrons in the source must have less than a 50:50 chance of moving over the barrier from the source to drain.

$$e^{-E_B/k_B T} < \frac{1}{2}$$

$$E_B > E_{\min} = k_B T \ln(2)$$



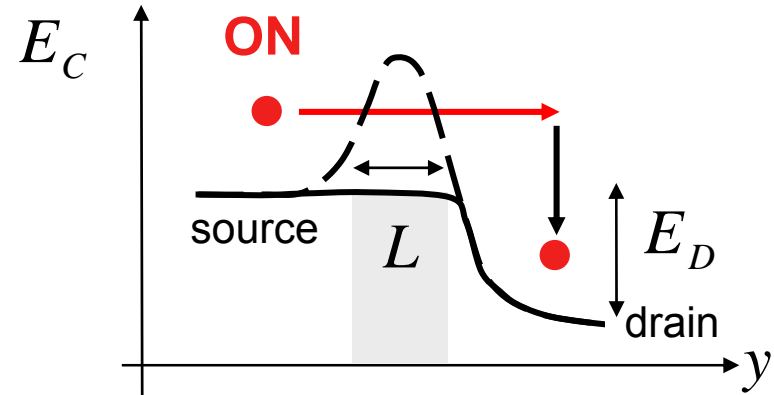
minimum switching energy (ii)

To distinguish **on** from **off**, electrons in the drain must have less than a 50:50 chance of moving over the barrier from the **drain to source**.

$$e^{-E_D / k_B T} < \frac{1}{2}$$

$$E_D > E_{\min} = k_B T \ln(2)$$

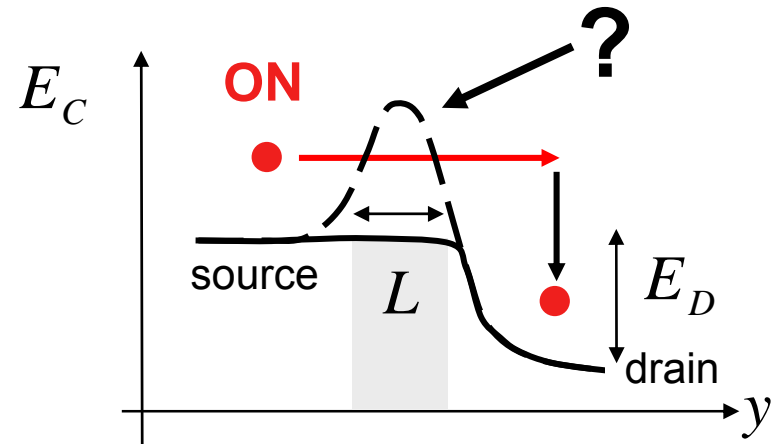
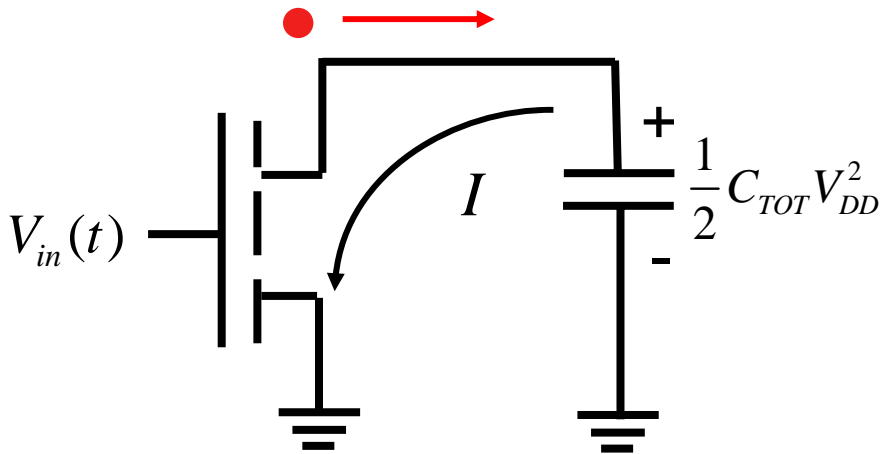
$$E_S > k_B T \ln(2) = 0.003 \text{ aJ}$$



(minimum energy dissipation per logic transition)

minimum switching energy (iii)

Does it take additional energy to move the gate-controlled barrier up and down?



$(k_B T \ln(2))$ **is** the min energy dissipation per logic transition)

minimum device size

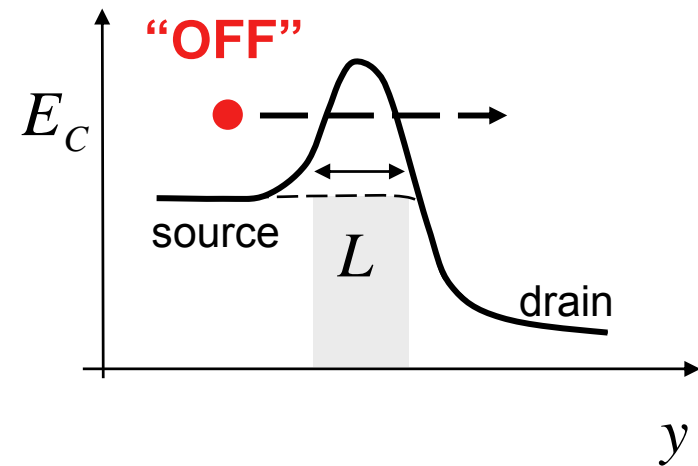
To distinguish **off** from **on**, the probability that an electron tunnels through the barrier must be less than a 50:50.

$$P(\text{WKB}) = \exp\left(-\frac{2\sqrt{2mE}}{\hbar}L\right) < \frac{1}{2}$$

$$L > \frac{\ln(2)}{2} \frac{\hbar}{\sqrt{2mE}}$$

$$E = k_B T = \frac{E_S(\text{min})}{\ln(2)}$$

$$L_{\text{min}} \approx \frac{\hbar}{\sqrt{2mE_S(\text{min})}} = 1.5 \text{ nm (300K)}$$



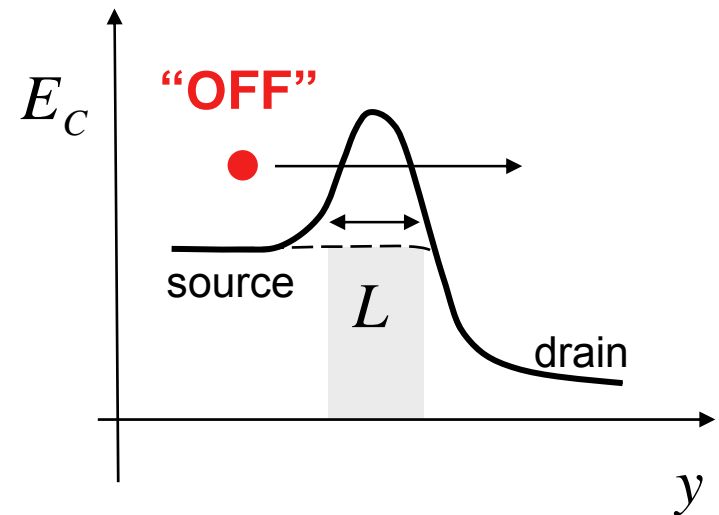
minimum device size (again)

$$\Delta p \Delta x > \hbar$$

$$\frac{\Delta p^2}{2m} = E_s (\text{min})$$

$$\Delta x = L$$

$$L_{\text{min}} \approx \frac{\hbar}{\sqrt{2mE_s (\text{min})}} = 1.5 \text{ nm (300K)}$$



minimum device size (iii)

Note also that the size of a device, S , must be larger than the size of its minimum element, L . (For a MOSFET, $S \sim 10-15L$.)

maximum device density

$$n_D (\text{max}) \approx \frac{1}{(10L_{\text{min}})^2} = 4.7 \times 10^{11} \text{ cm}^{-2}$$

We will show later that device density is limited by the maximum power density that can be dissipated - not by device size.

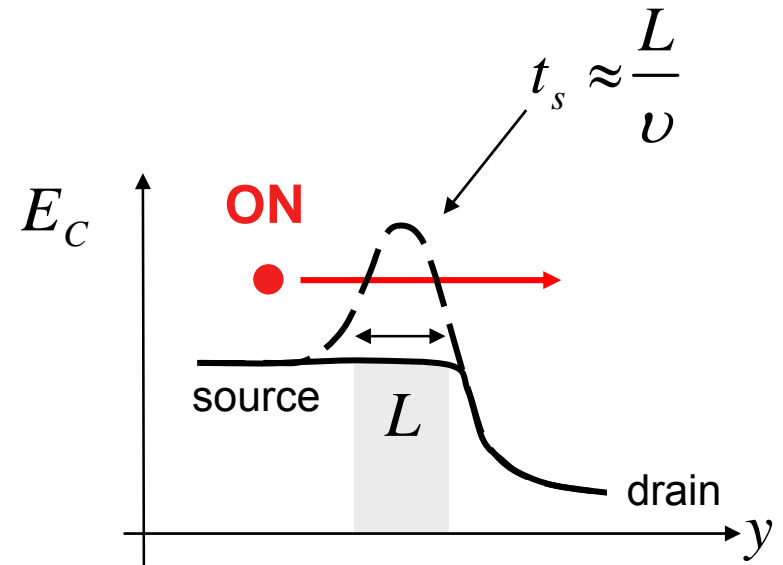
maximum device speed

The minimum device transit time sets the maximum speed.

$$t_s(\text{min}) \approx \frac{L_{\text{min}}}{v} = \frac{L_{\text{min}}}{\sqrt{2E/m}}$$

$$E = k_B T = \frac{E_s(\text{min})}{\ln(2)}$$

$$L_{\text{min}} \approx \frac{h}{\sqrt{2mE_s(\text{min})}}$$



$$t_s(\text{min}) \approx \frac{h}{E_s(\text{min})} = 0.04 \text{ ps} \quad (300\text{K})$$

$$\Delta E \Delta t = \hbar$$

power dissipation

$$P_D = \frac{\alpha n_D E_S}{t_S}$$

$$\alpha = 1, \quad n_D(\text{max}), \quad E_S(\text{min}), \quad t_S(\text{min})$$

$$P_D = 3.7 \times 10^4 \text{ W/cm}^2$$

surface of the sun: $6 \times 10^3 \text{ W/cm}^2$

forced water cooling: $< 800 \text{ W/cm}^2$

ITRS: $< 100 \text{ W/cm}^2$

power-limited device density

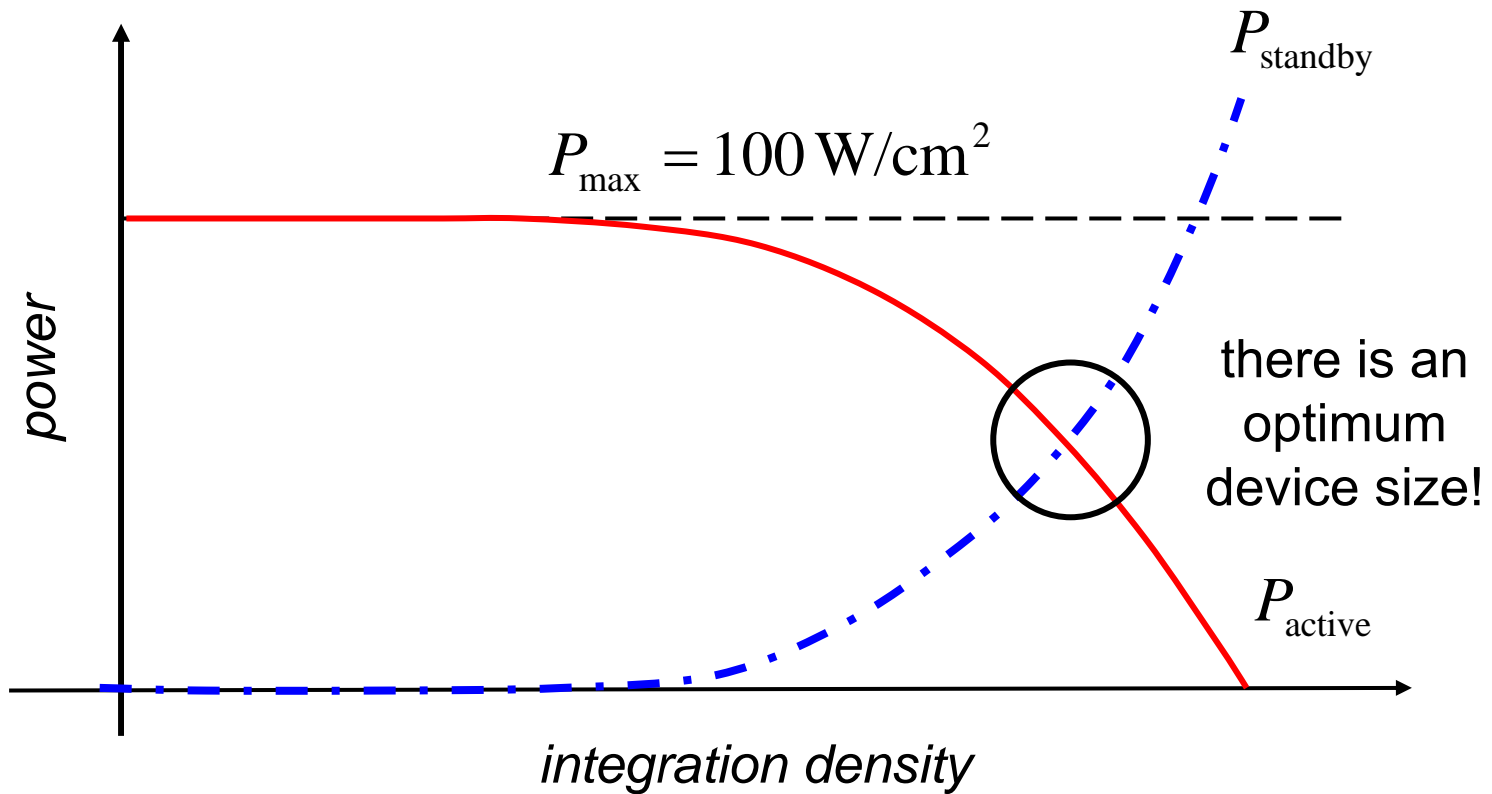
maximum power dissipation per unit area limits density
- not our ability to make devices small.

$$\hat{n}_D(\text{max}) = \frac{P_{\text{max}} t_S(\text{min})}{\alpha E_S(\text{min})}$$

for $P_{\text{max}} = 100 \text{ W/cm}^2$ and $\alpha = 1$

$$\hat{n}_D(\text{max}) \sim 1.5 \times 10^9 \quad \text{devices/cm}^2$$

power-constrained design



power-delay product

$$P_D \tau = \frac{E_S}{t_S} t_S = E_S$$

$$P_D \tau \Big|_{\min} = E_S \Big|_{\min} = k_B T \ln 2$$

But....this metric does not capture the fact that we usually want to runs circuits fast and at low power.

energy-delay product

$$E\tau|_{\min} = E_S t_S|_{\min} = E_S(\min) \frac{h}{E_S(\min)} = h$$

$$(\Delta E \Delta t > h)$$

summary

1) Switching energy: $E_S > k_B T \ln(2)$

2) Switching delay: $t_S > \hbar/E_S$ (min)

3) Device size: $L_{\min} > \hbar/\sqrt{2mE_S}$ (min)

4) Device density: $\hat{n}_D < P_{\max} t_S$ (min)/ E_S (min)

5) Energy-delay: $E\tau > \hbar$

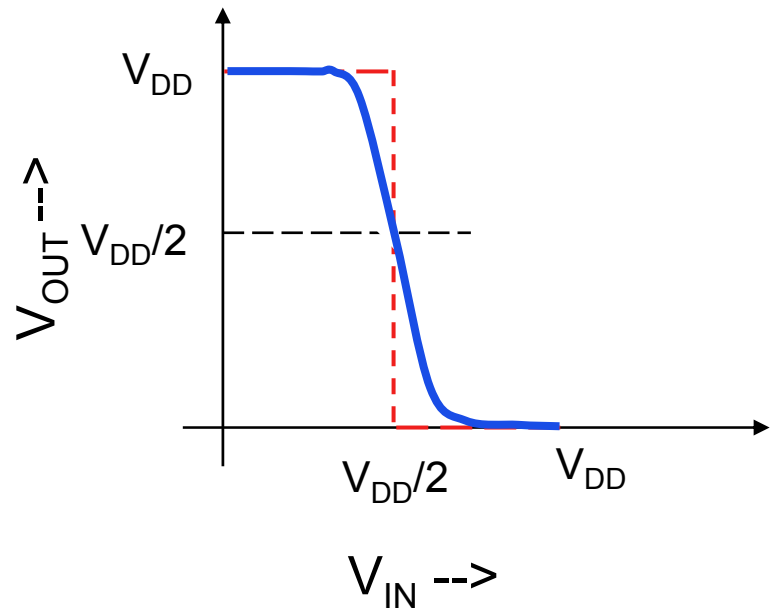
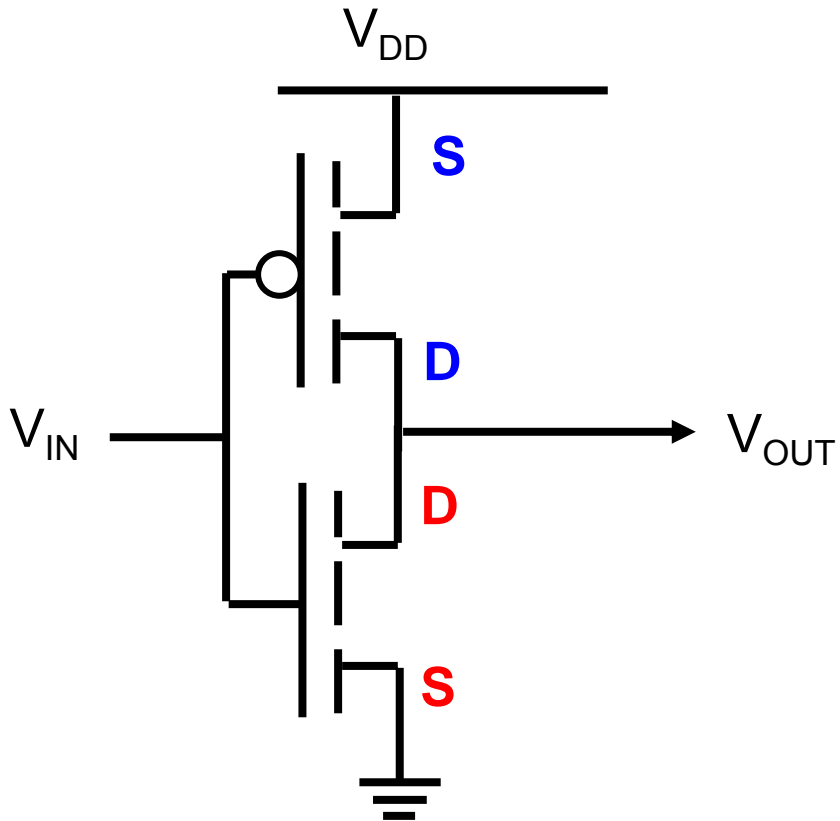
comparison to 65nm CMOS

parameter	65nm ITRS	Limit	65nm /Limit
E_s (aJ)	23	0.003	8000
τ (fs)	640	40	16
L (nm)	25 nm	1.5 nm	17
\hat{n}_s (cm ⁻²)	0.8×10^9	1.5×10^9	0.5
$E\tau$ (J-s)	1.5×10^{-29}	1.1×10^{-34}	136,000

outline

- 1) CMOS Metrics
- 2) MOSFET limits
- 3) Circuit limits**
- 4) System limits

minimum V_{DD}



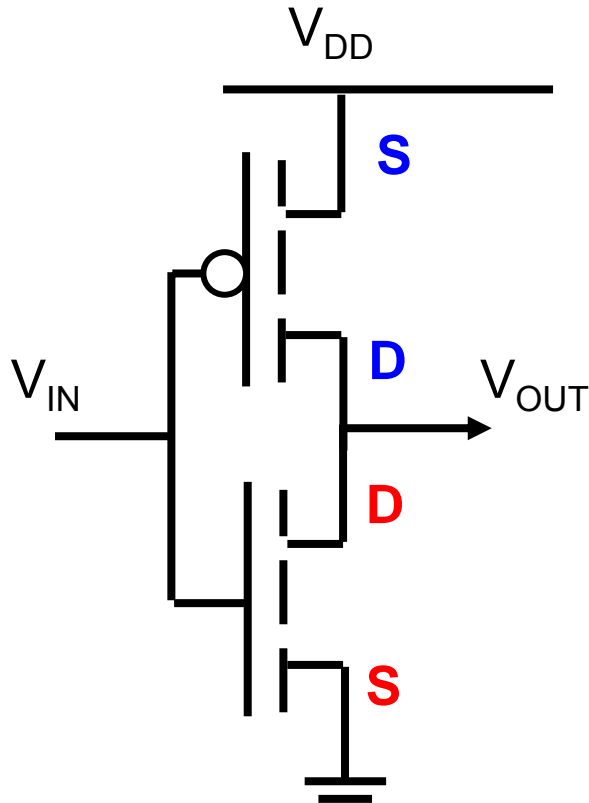
Question: What is the smallest V_{DD} for a CMOS inverter?

Answer: The smallest V_{DD} that gives a gain > 1

reference

J.D. Meindl and J.A. Davis, “*The Fundamental Limit on Binary Switchin Energy for Terascale Integration*, *IEEE J. Solid-State Circuits*, **35**, pp. 1515-1516, 2000.

minimum V_{DD}



assume subthreshold operation:

$$I_D = K e^{q(V_{GS} - V_T)/mk_B T} \left(1 - e^{-qV_{DS}/k_B T} \right)$$

$$I_{DN} = K_N e^{q(V_{in} - V_{TN})/mk_B T} \left(1 - e^{-qV_{out}/k_B T} \right)$$

$$I_{DP} = K_P e^{q(V_{DD} - V_{in} + V_{TP})/mk_B T} \left(1 - e^{q(V_{out} - V_{DD})/k_B T} \right)$$

$$I_{DN} = I_{DP} \rightarrow V_{out}(V_{in})$$

minimum V_{DD} (ii)

$$K_N e^{q(V_{in} - V_{TN})/mk_B T} \left(1 - e^{-qV_{out}/k_B T}\right) = K_P e^{q(V_{DD} - V_{in} + V_{TP})/mk_B T} \left(1 - e^{q(V_{out} - V_{DD})/k_B T}\right)$$

$$\left. \begin{array}{l} K_N = K_P = K \\ V_{TN} = V_T = -V_{TP} \\ m = 1 \end{array} \right\} \text{ solve for } A_V = \frac{dV_{out}}{dV_{in}} = f(V_{DD})$$

$$|A_V| > 1 \Rightarrow V_{DD} > 2 \ln(2) \frac{k_B T}{q}$$

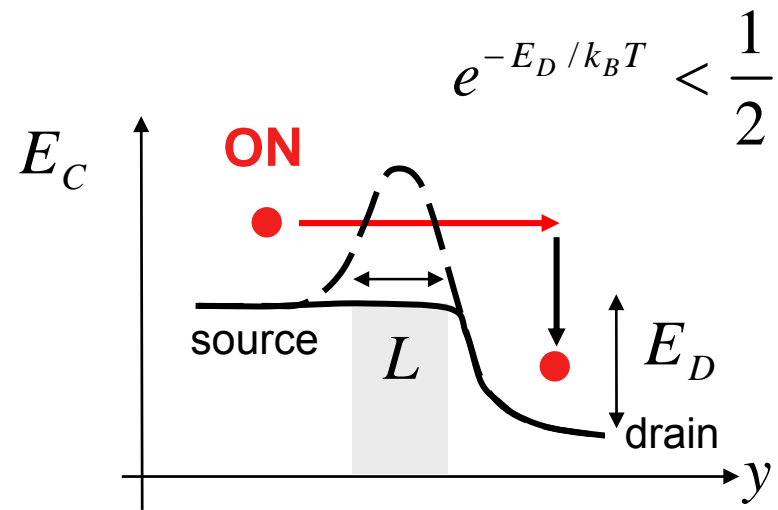
$$V_{DD}|_{\min} = 2 \ln(2) \frac{k_B T}{q}$$

minimum V_{DD} (iii)

$$E_D > E_{D\min} = k_B T \ln(2)$$

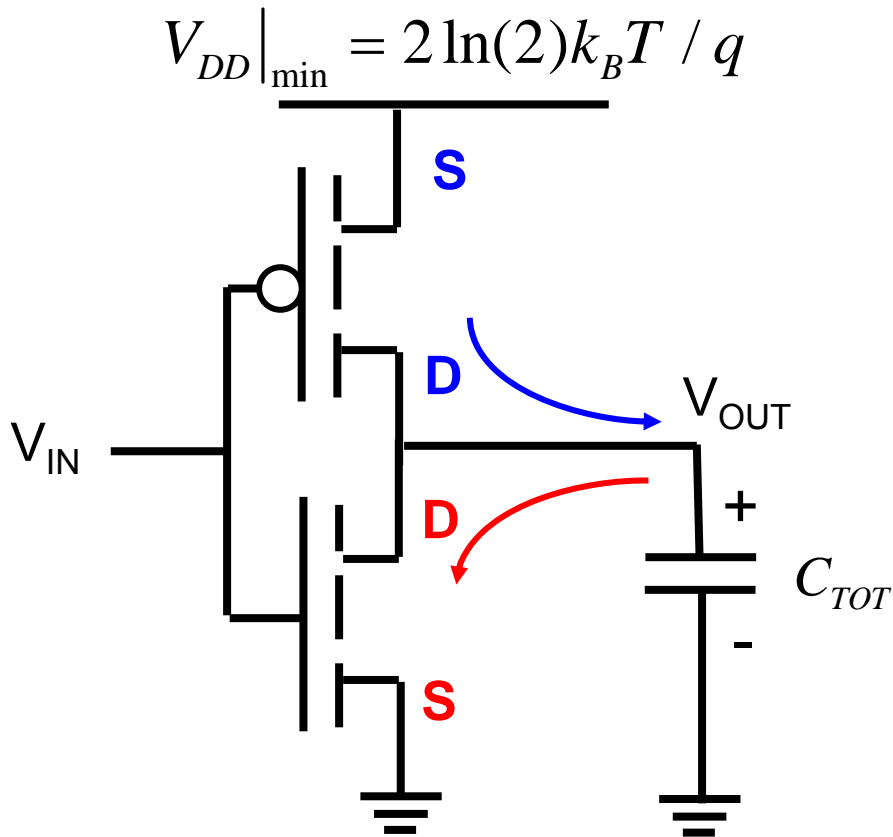
$$V_{DD}|_{\min} = E_{D\min} / q = \frac{k_B T}{q} \ln(2)$$

2 MOSFETS in series \Rightarrow



$$V_{DD}|_{\min} = 2 \ln(2) \frac{k_B T}{q}$$

minimum switching energy



$$E_S = \frac{1}{2} C_{TOT} V_{DD}^2$$

$$E_S = \frac{1}{2} Q V_{DD}$$

$$Q|_{\min} = q$$

$$E_S = \frac{1}{2} Q|_{\min} V_{DD}|_{\min}$$

$$E_S = k_B T \ln(2)$$

outline

- 1) CMOS Metrics
- 2) MOSFET limits
- 3) Circuit limits
- 4) **System limits**

circuit performance

	device	CPU circuit	increase
delay:	0.64 ps	250 ps	$\sim 400 \times$
switching energy:	23 aJ	6000 aJ	$\sim 300 \times$
energy-delay:	$\sim 10^{-29}$ J-s	$\sim 10^{-24}$ J-s	$\sim 100,000 \times$

circuits and fundamental limits

parameter	CPU circuit	Limit	circuit /limit
E_s (aJ)	6000	0.003	2,000,000
τ (fs)	250,000	40	6250
$E\tau$ (J-s)	1.4×10^{-24}	1.1×10^{-34}	$\sim 10^{10}$

Since 1960, switching energy has decreased by about 5 orders of magnitude. (J.D. Meindl, Q. Chen, and J.A. Davis, "Limits on Silicon Nanoelectronics for Terascale Integration," *Science*, **239**, pp. 2044-2049, 2001)

chip performance index

$$B = \frac{N}{\tau_s} \text{ ops / cm}^2\text{-s}$$

$$CPI = \frac{N}{\tau_s} \times \frac{1}{(E_s/t_s)} = \frac{N}{E_s} \text{ ops / s-cm}^2\text{-W}$$

$CPI : 10^{23}$ (today's high-performance logic)

$CPI|_{\text{ultimat}} : 10^{32}$ (since 1960, the CPI has increased by factor of $\sim 10^{14}$)

J.D. Meindl, "Low Power Microelectronics: Retrospect and Prospect,"
Proc. IEEE, **83**, 619-635, 1995

summary

- 1) Key device metrics include size, switching energy, and speed.
- 2) Key system metrics include density, switching energy, speed, and power.
- 3) Device metrics are 'approaching' fundamental limits.
- 4) System metrics are a long way from fundamental limits.

outline

- 1) CMOS Metrics
- 2) MOSFET limits
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- 4) System limits